

WHAT IS CLAIMED IS:

1. A photoreactive resin composition comprising:
a powdered base metal;
an organic binder;
a photosensitive organic component; and
a polycarboxylic acid-based dispersing agent with a molecular weight of about 1,500 or less.
2. A photoreactive resin composition according to Claim 1, wherein the molecular weight of the organic binder is about 10,000 or more.
3. A photoreactive resin composition according to Claim 2, wherein the polycarboxylic acid-based dispersing agent content is about 0.05 to 0.8 parts by weight relative to 100 parts by weight of the powdered base metal.
4. A photoreactive resin composition according to Claim 3, further comprising a polyvalent alcohol and a thixotropic agent.
5. A photoreactive resin composition according to Claim 4, wherein the molecular weight of the organic binder is about 60,000 or less.

6. A photoreactive resin composition according to Claim 1, wherein the polycarboxylic acid-based dispersing agent content is about 0.05 to 0.8 parts by weight relative to 100 parts by weight of the powdered base metal.

7. A photoreactive resin composition according to Claim 1, further comprising a polyvalent alcohol and a thixotropic agent.

8. A photoreactive resin composition according to Claim 1, wherein the molecular weight of the organic binder is about 60,000 or less.

9. In a method for making a circuit substrate comprising the step of forming a conductive pattern using a photoreactive resin composition, utilizing a photoreactive composition according to Claim 6.

10. In a method for making a circuit substrate comprising the step of forming a conductive pattern using a photoreactive resin composition, utilizing a photoreactive composition according to Claim 4.

11. In a method for making a circuit substrate comprising the step of forming a conductive pattern using a photoreactive resin composition, utilizing a photoreactive composition according to Claim 2.

12. In a method for making a circuit substrate comprising the step of forming a conductive pattern using a photoreactive resin composition, utilizing a photoreactive composition according to Claim 1.

13. A method for making a circuit substrate comprising the steps of:
applying a photoreactive resin composition according to Claim 1 onto a support:

exposing and developing the photoreactive resin composition to form a predetermined conductive pattern on the support;

transferring the conductive pattern from the support to a substrate; and
firing the conductive pattern.

14. A method for making a ceramic multilayer substrate according to Claim 13, wherein the substrate is a ceramic green sheet; and wherein a plurality of ceramic green sheets with the conductive patterns are stacked to form a laminate prior to the firing.

15. A method for making a circuit substrate comprising the steps of:
applying a photoreactive resin composition according to Claim 4 onto a support:

exposing and developing the photoreactive resin composition to form a predetermined conductive pattern on the support;

transferring the conductive pattern from the support to a substrate; and
firing the conductive pattern.

16. A method for making a ceramic multilayer substrate according to Claim 15, wherein the substrate is a ceramic green sheet; and wherein a plurality of ceramic green sheets with the conductive patterns are stacked to form a laminate prior to the firing.

17. A method for making a circuit substrate comprising the steps of:
applying a photoreactive resin composition according to Claim 2 onto a support:
exposing and developing the photoreactive resin composition to form a predetermined conductive pattern on the support;
transferring the conductive pattern from the support to a substrate; and
firing the conductive pattern.

18. A method for making a ceramic multilayer substrate according to Claim 17, wherein the substrate is a ceramic green sheet; and wherein a plurality of ceramic green sheets with the conductive patterns are stacked to form a laminate prior to the firing.

19. A method for making a circuit substrate comprising the steps of:
applying a photoreactive resin composition according to Claim 1 onto a support:
exposing and developing the photoreactive resin composition to form a predetermined conductive pattern on the support;
transferring the conductive pattern from the support to a substrate; and
firing the conductive pattern.

20. A method for making a ceramic multilayer substrate according to Claim 19, wherein the substrate is a ceramic green sheet; and wherein a plurality of ceramic green sheets with the conductive patterns are stacked to form a laminate prior to the firing.